

ABSTRACT OF THE DISCLOSURE

An improved memory module and method of manufacture are presented. The memory module takes on the same outer dimensions as conventional memory cards. The memory module includes an integrated circuit and a conductor encased within molded resin. The conductor can be taken from a tape or a lead frame, and can include bumps or wires extending from the conductor to corresponding bonding pads on the integrated circuit. The bonded integrated circuit can thereafter be placed within a cavity formed inside a mold housing, where resin may be injected to form the memory module. The conductor can also be shaped so as to extend on multiple planes from the connection point on or near the bonding pad to an edge connector residing near one edge only of the memory module. The conductor thereby serves as an integrated signal carrier which receives connection to the integrated circuit and provides slide-in, releasable coupling to a receptor normally designed to receive conventional memory cards. The portion of the conductor that suffices as the edge connector is configured as a pad that has an outer surface substantially flush with an outer surface of the memory module for abutment against planar conductive elements within the receptor.